Available at Digi-Key

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OH320-CC Series Ultra Stable OCXO



Description:

Connor-Winfield's Series OH320-CC is a high precision Enhanced Oven Compensated Crystal Oscillator (OCXO) in a small 22x25.4mm surface mount package. The OH320-CC Series provides thermal stability of less than ±1ppb and is designed for applications demanding excellent frequency stability and excellent phase noise.

Features:

- Output Frequency: 10.0, 12.8, 20.0, 25.0, or 100.0 MHz
- 3.3 or 5.0 Vdc Operation
- 22 x 25.4 mm SMT Package
- Frequency Stabilities: ±1ppb or ±0.5ppb
- Temperature Ranges: -40 to 85°C or -20 to 70°C
- CMOS or Sine Output
- Grounded Metal Cover

Absolute Maximum Ratings

Parameter	Minimum	Nominal	Maximum	Units	Notes
Storage Temperature	-55	-	105	°C	
Supply Voltage (Vcc)	-0.5	-	5.5	Vdc	
Operating Supply Voltage 3.3V	3.135	3.30	3.465	Vdc	
Operating Supply Voltage 5.0V	4.75	5.0	5.25	Vdc	

Absolute Ratings: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only. The functional operation of the device at those or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to conditions outside the "recommended operating conditions" for any extended period of time may adversely impact device reliability and result in failures not covered by warranty.

Operating Specifications

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Parameter	Minimum	Nominal	Maximum	Units	Notes
Center Frequency (Fo)	10.0, 1	2.8, 20.0, 25.0,	or 100.0	MHz	
Operating Temperature					
Option 6	-40	-	85	°C	
Option 7	-20	-	70	°C	
Frequency Calibration @ 25°C	-200	-	200	ppb	
Frequency Stability vs. Temperatur	re				
Option 01	-1.0	-	1.0	ppb	1
Option 005	-0.5	-	0.5	ppb	1
Frequency vs. Supply Voltage	-0.2	-	0.2	ppb	Vcc±1%
Frequency vs. Load	-0.2	-	0.2	ppb	Vcc±1%
Aging: Daily	-0.5	-	0.5	ppb/day	2
Aging: First Year	-50	-	50	ppb	
Lifetime Tolerance: (20 years)	-400	-	400	ppb	3
Supply Voltage (Vcc)					
Option 03	3.135	3.30	3.465	Vdc	4
Option 05	4.75	5.0	5.25	Vdc	4
Power Consumption:					
Steady State, @ 25°C, 3.3Vdc	-	-	1.5	W	5
Turn Ón 3.3Vdc	-	-	3.6	W	5
Steady State, @ 25°C, 5.0Vdc	-	-	2.5	W	5
Turn On 5.0Vdc	-	-	4.2	W	5
Phase Jitter: (BW: 10 Hz to Fo/2)	-	-	1.0	ps rms	
Allan Deviation (Tau=10s) for Fo=10M	1Hz -	2.0E-12	1.0E-11	·	
Start-Up Time:	-	-	500	ms	
Warm Up Time: @ 25°C	-	-	5	minutes	6



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Phase Noise

Parameter	Minimum	Nominal	Maximum	Units	Notes
SSB Phase Noise at 1Hz offset	-	-90	-85	dBc/Hz	
SSB Phase Noise at 10Hz offset	-	-120	-115	dBc/Hz	
SSB Phase Noise at 100Hz offset	-	-140	-140	dBc/Hz	
SSB Phase Noise at 1KHz offset	-	-154	-150	dBc/Hz	
SSB Phase Noise at 10KHz offset	-	-260	-155	dBc/Hz	
SSB Phase Noise at 100KHz offset	-	-163	-160	dBc/Hz	

CMOS Output Characteristics

Parameter	Minimum	Nominal	Maximum	Units	Notes
Load	-	15	-	pF	
Output Voltage: High (Voh)	3.0	-	-	V	
Low (Vol)	-	-	0.4	V	
Output Current: High (Ioh)	-0.4	-	-	mA	
Low (IoI)	-	-	0.4	mA	
Duty Cycle at 50% of Vcc	45	50	55	%	
Rise / Fall Time: 10% to 90%	-	-	6	ns	
Spurious Output	-	-	-80	dBc	

Sinewave Output Characteristics

Parameter	Minimum	Nominal	Maximum	Units	Notes
Load	-	50	-	Ohms	
Output Power	5	7	9	dBm	
Harmonics	-	-	-40	dBc	
Spurious	-	-	-70	dBc	

Notes:

Frequency stability is based on (Fmax-Fmin)/2.
At time of shipment after 48 hours of operation.

Inclusive of Calibration, Operating Temperature, Supply Voltage change, Load change, and 10 Year Aging.
Supply voltage must reach Vcc levels monotonically within a ramp-up time of <12 ms.

5. Measured with Vcc = Nominal in calm air. 6 Measured @ 25° C, within ±100 ppb, referenced one hour after turn-on.

Re-Stabilization Time

Off Time	Re stabilization Time	
<1 Hour	<2 Hours *	
<6 Hour	<12 Hours *	
<24 Hour	<48 Hours *	
1 to 16 Days	48 Hours + 1/4 Off Time *	
>16 Days	<6 Days *	

* For a given off time, the time required to meet daily aging, short term stability requirements.

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Attention: System Designers please review Application Note AN2093: System Design Information and Printed Circuit Board Layout Guidelines for OCXO Oscillators. @ www.conwin.com/support.html

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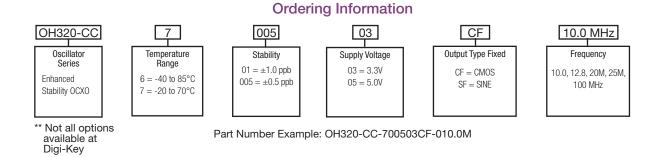
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	Package Characteristics
OH320 Package	Package consists of a hermetic metal package OCXO mounted to an FR4 substrate surrounded
	by a non-hermetic metal cover (airflow shield)

Environmental Characteristics

Shock	500 G's 1ms, Halfsine, 3 shocks per direction, per MIL-STD 202G, Method 213B Test Condition D.
Sinusoidal Vibration	0.06" D.A. or 10G's Peak, 10 to 500 Hz, per MIL-STD-202G, Method 204D, Test Condition A.
Random Vibration	5.35 G's rms. 20 to 2000 Hz per MIL-STD-202G, Method 214, Test Condition 1A, 15 minutes each axis.
Moisture	10 cycles, 95% RH, Per MIL-STD-202G, Method 112.
Marking Permanency	Per MIL-STD-202G, Method 215J.
Solder Process Recommendations:	RoHS compliant, lead free. See solder profile on page 5.
In-line reflow:	Refer to recommended reflow pre-heat and reflow temperatures on page 5. Package material
	consists of metal cover with FR4 substrate. Component solder is Pb-free high temperature
	eutectic alloy with melting point of 221°C. Product should not be inverted during reflow.
Removal of device:	If for any reason the device needs to be removed from the board, use a temperature controlled
	repair station with profile monitoring capabilities. Following a monitored profile will insure the
	device is properly pre-heated prior to relow. Refer to IPC 610E for inspection guidelines.
Recommended Cleaning Process:	(If required)
	Device is non-hermetic, water resistance with four weep holes, one in each corner to allow
	moisture to be removed during the drying cycle. We recommend in-line warm water wash
	with air knife and drying capabilities. If cleaner does not have drying capability, then use hot air
	circulated oven. Boards should be placed in the oven vertically for good water runoff
	Device must be dried properly prior to use!
Note: If saponifier is used make sure	the device is rinsed properly to insure all residues are removed. PH of saponifier should not exceed 10.
Drying Temperature:	Between 85 to 100°C.
Drying Time:	Time will vary depending on the board size.
Caution: Do not submerge the o	device!





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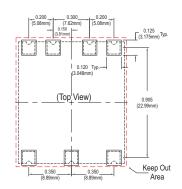
Package Outline 0.866+/-0.008 (22.00+/-0.20mm) 0.300 0.200 7.62mm) (5.08mm) 5 4 1.000+/-0.008 (25.40+/-0.20mm) (Bottom View) 0.350 Pin 1 Typical Pad Size (8.89mm) 0.700 0.100 x 0.100 (17.78mm) (2.54 x 2.54mm) 7 Places 0.062 0.567 (1.57mm)(14.40mm) **Dimensional Tolerance** +/-0.005 (0.127mm)

Pad Termination Finish: Gold Flash <10 micro inches

Marking Information

Date Code (YYWW) **Model Number** OH320-CC-700503CF **Output Frequency** Serial # Barcode **Serial Number**

Suggested Pad Layout

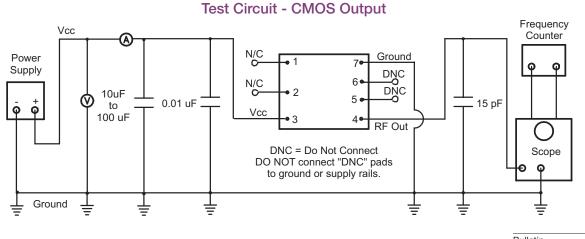


* Do not route any traces in the keep out area. It is recommended the next layer under the keep out area is to be ground plane.

Pad Connections

Pad	Connection
1:	N/C
2:	Do not Connect
3:	Supply Voltage (Vcc)
4:	RF Output
5:	Do Not Connect
6:	Do Not Connect
7:	Ground
DO	

DO NOT connect "DNC" pads to ground or supply rails.



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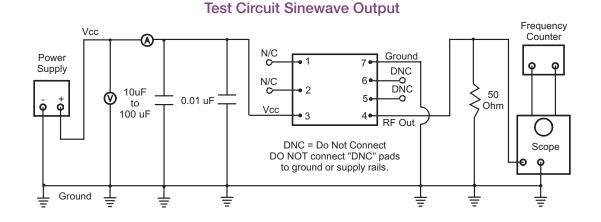
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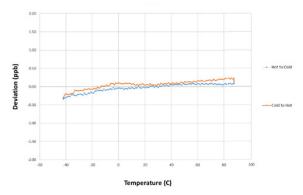
1

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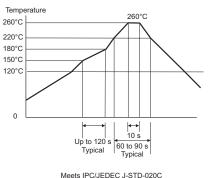




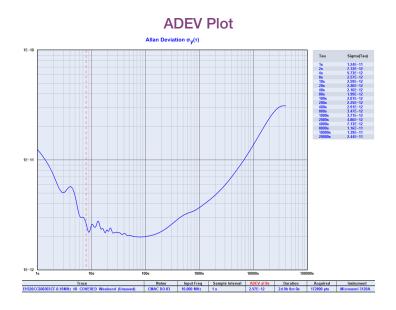
Frequency Stability Plot over Temperature



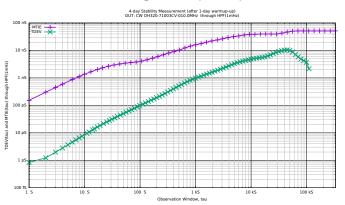








TDEV & MTIE 4-Day Stability Measurement Through HPF (1MHz)

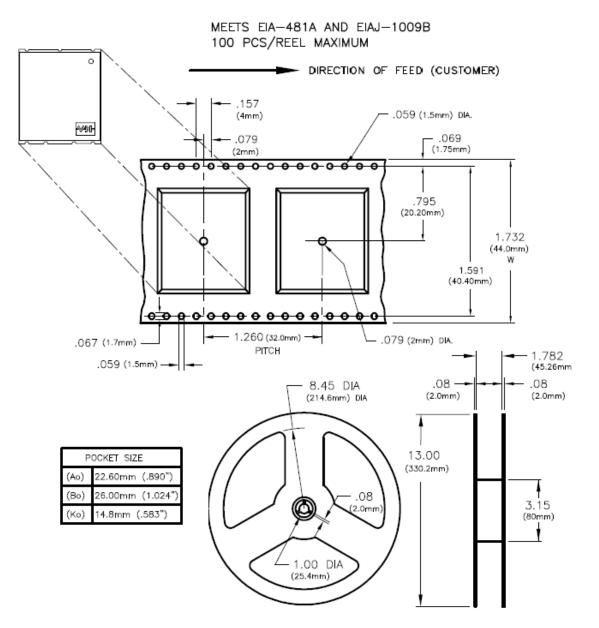


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Tape and Reel Information



Revision History

Revision	Date	Changes		
00	12/05/19	Initial Release		
01	10/28/20	Change part number series name		
02	12/22/20	Update stability specifications, added Tape and Reel drawings	Bulletin	Cx309
03	02/27/24	Update phase noise, reflow recommendations, and add Digi-Key availability.	Page	6 of 6
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